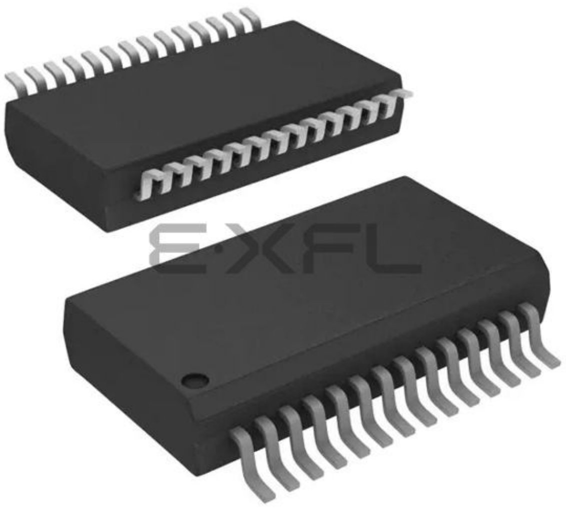


What is "Embedded - Microcontrollers"?

"Embedded - Microcontrollers" refer to small, integrated circuits designed to perform specific tasks within larger systems. These microcontrollers are essentially compact computers on a single chip, containing a processor core, memory, and programmable input/output peripherals. They are called "embedded" because they are embedded within electronic devices to control various functions, rather than serving as standalone computers. Microcontrollers are crucial in modern electronics, providing the intelligence and control needed for a wide range of applications.

Applications of "Embedded - Microcontrollers"

Details	
Product Status	Active
Core Processor	MIPS32® M4K™
Core Size	32-Bit Single-Core
Speed	40MHz
Connectivity	I²C, IrDA, LINbus, PMP, SPI, UART/USART, USB OTG
Peripherals	Brown-out Detect/Reset, DMA, I²S, POR, PWM, WDT
Number of I/O	19
Program Memory Size	64KB (64K x 8)
Program Memory Type	FLASH
EEPROM Size	-
RAM Size	16K x 8
Voltage - Supply (Vcc/Vdd)	2.3V ~ 3.6V
Data Converters	A/D 9x10b
Oscillator Type	Internal
Operating Temperature	-40°C ~ 85°C (TA)
Mounting Type	Surface Mount
Package / Case	28-SSOP (0.209", 5.30mm Width)
Supplier Device Package	28-SSOP
Purchase URL	https://www.e-xfl.com/product-detail/microchip-technology/pic32mx230f064bt-i-ss

Coprocessor 0 also contains the logic for identifying and managing exceptions. Exceptions can be caused by a variety of sources, including alignment errors in data, external events or program errors. Table 3-3 lists the exception types in order of priority.

TABLE 3-3: MIPS32® M4K® PROCESSOR CORE EXCEPTION TYPES

Exception	Description
Reset	Assertion $\overline{MCLR}$ or a Power-on Reset (POR).
DSS	EJTAG debug single step.
DINT	EJTAG debug interrupt. Caused by the assertion of the external *EJ_DINT* input or by setting the EjtagBrk bit in the ECR register.
NMI	Assertion of NMI signal.
Interrupt	Assertion of unmasked hardware or software interrupt signal.
DIB	EJTAG debug hardware instruction break matched.
AdEL	Fetch address alignment error. Fetch reference to protected address.
IBE	Instruction fetch bus error.
DBp	EJTAG breakpoint (execution of `SDBBP` instruction).
Sys	Execution of `SYSCALL` instruction.
Bp	Execution of `BREAK` instruction.
RI	Execution of a reserved instruction.
CpU	Execution of a coprocessor instruction for a coprocessor that is not enabled.
CEU	Execution of a `CorExtend` instruction when `CorExtend` is not enabled.
Ov	Execution of an arithmetic instruction that overflowed.
Tr	Execution of a trap (when trap condition is true).
DDBL/DDBS	EJTAG Data Address Break (address only) or EJTAG data value break on store (address + value).
AdEL	Load address alignment error. Load reference to protected address.
AdES	Store address alignment error. Store to protected address.
DBE	Load or store bus error.
DDBL	EJTAG data hardware breakpoint matched in load data compare.

3.3 Power Management

The MIPS M4K processor core offers many power management features, including low-power design, active power management and power-down modes of operation. The core is a static design that supports slowing or Halting the clocks, which reduces system power consumption during Idle periods.

3.3.1 INSTRUCTION-CONTROLLED POWER MANAGEMENT

The mechanism for invoking Power-Down mode is through execution of the `WAIT` instruction. For more information on power management, see **Section 26.0 "Power-Saving Features"**.

3.4 EJTAG Debug Support

The MIPS M4K processor core provides an Enhanced JTAG (EJTAG) interface for use in the software debug of application and kernel code. In addition to standard User mode and Kernel modes of operation, the M4K core provides a Debug mode that is entered after a debug exception (derived from a hardware breakpoint, single-step exception, etc.) is taken and continues until a Debug Exception Return (`DERET`) instruction is executed. During this time, the processor executes the debug exception handler routine.

The EJTAG interface operates through the Test Access Port (TAP), a serial communication port used for transferring test data in and out of the core. In addition to the standard JTAG instructions, special instructions defined in the EJTAG specification define which registers are selected and how they are used.

4.0 MEMORY ORGANIZATION

Note: This data sheet summarizes the features of the PIC32MX1XX/2XX 28/36/44-pin Family of devices. It is not intended to be a comprehensive reference source.For detailed information, refer to **Section 3. "Memory Organization"** (DS60001115), which is available from the *Documentation > Reference Manual* section of the Microchip PIC32 web site (www.microchip.com/pic32).

PIC32MX1XX/2XX 28/36/44-pin Family microcontrollers provide 4 GB unified virtual memory address space. All memory regions, including program, data memory, Special Function Registers (SFRs), and Configuration registers, reside in this address space at their respective unique addresses. The program and data memories can be optionally partitioned into user and kernel memories. In addition, the data memory can be made executable, allowing PIC32MX1XX/2XX 28/36/44-pin Family devices to execute from data memory.

Key features include:

- 32-bit native data width
- Separate User (KUSEG) and Kernel (KSEG0/KSEG1) mode address space
- Flexible program Flash memory partitioning
- Flexible data RAM partitioning for data and program space
- Separate boot Flash memory for protected code
- Robust bus exception handling to intercept runaway code
- Simple memory mapping with Fixed Mapping Translation (FMT) unit
- Cacheable (KSEG0) and non-cacheable (KSEG1) address regions

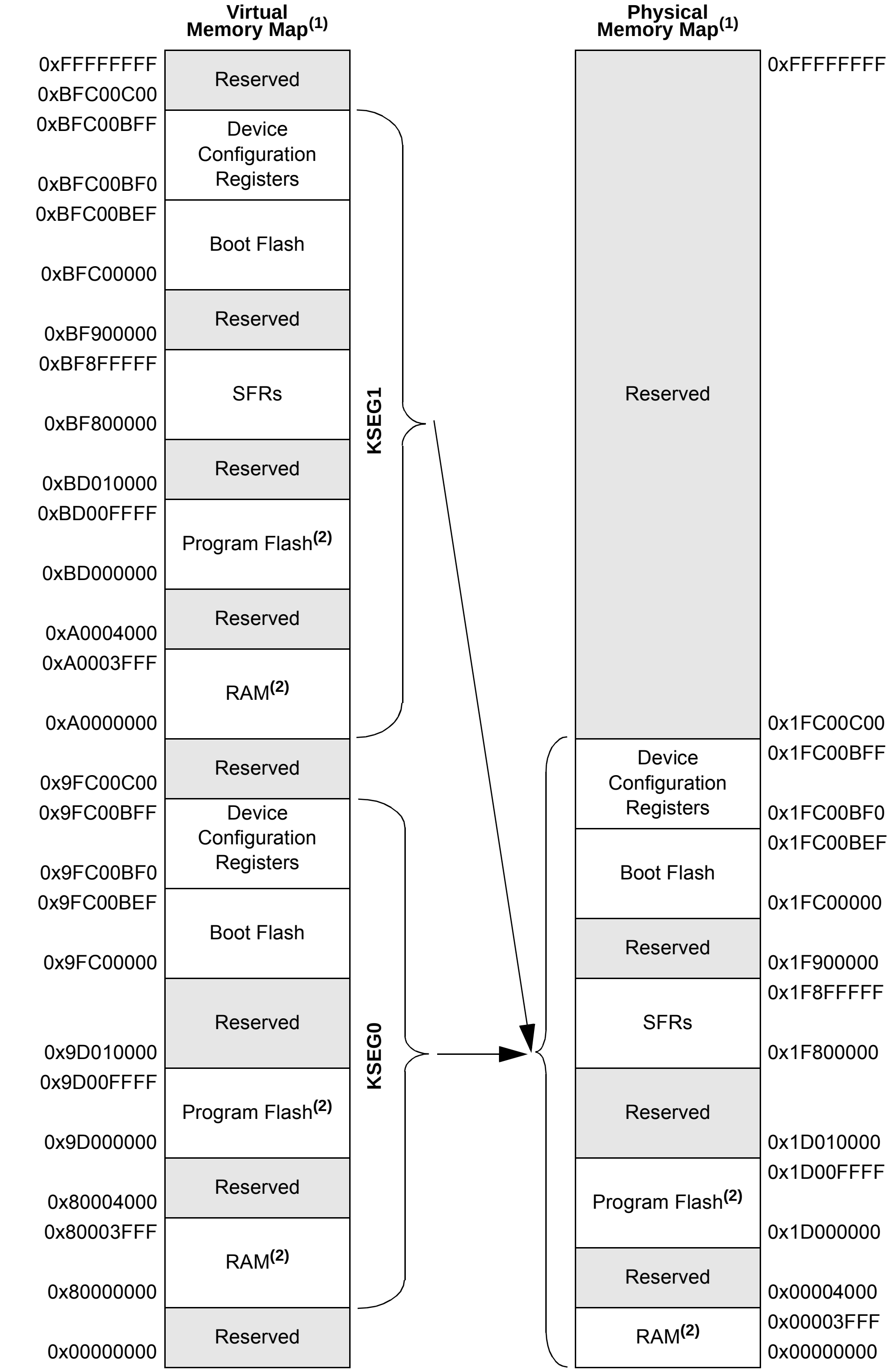
4.1 PIC32MX1XX/2XX 28/36/44-pin Family Memory Layout

PIC32MX1XX/2XX 28/36/44-pin Family microcontrollers implement two address schemes: virtual and physical. All hardware resources, such as program memory, data memory and peripherals, are located at their respective physical addresses. Virtual addresses are exclusively used by the CPU to fetch and execute instructions as well as access peripherals. Physical addresses are used by bus master peripherals, such as DMA and the Flash controller, that access memory independently of the CPU.

The memory maps for the PIC32MX1XX/2XX 28/36/44-pin Family devices are illustrated in Figure 4-1 through Figure 4-6.

Table 4-1 provides SFR memory map details.

FIGURE 4-3: MEMORY MAP ON RESET FOR PIC32MX130/230 DEVICES (16 KB RAM, 64 KB FLASH)



Note 1: Memory areas are not shown to scale.

2: The size of this memory region is programmable (see **Section 3. "Memory Organization"** (DS60001115) in the *"PIC32 Family Reference Manual"*) and can be changed by initialization code provided by end-user development tools (refer to the specific development tool documentation for information).

7.0 INTERRUPT CONTROLLER

Note:	This data sheet summarizes the features of the PIC32MX1XX/2XX 28/36/44-pin Family of devices. It is not intended to be a comprehensive reference source. To complement the information in this data sheet, refer to **Section 8. "Interrupt Controller"** (DS60001108), which is available from the *Documentation > Reference Manual* section of the Microchip PIC32 web site (www.microchip.com/pic32).

PIC32MX1XX/2XX 28/36/44-pin Family devices generate interrupt requests in response to interrupt events from peripheral modules. The interrupt control module exists externally to the CPU logic and prioritizes the interrupt events before presenting them to the CPU.

The PIC32MX1XX/2XX 28/36/44-pin Family interrupt module includes the following features:

- Up to 64 interrupt sources
- Up to 44 interrupt vectors
- Single and multi-vector mode operations
- Five external interrupts with edge polarity control
- Interrupt proximity timer
- Seven user-selectable priority levels for each vector
- Four user-selectable subpriority levels within each priority
- Software can generate any interrupt
- User-configurable Interrupt Vector Table (IVT) location
- User-configurable interrupt vector spacing

Note:	The dedicated shadow register set is not present on PIC32MX1XX/2XX 28/36/44-pin Family devices.

A simplified block diagram of the Interrupt Controller module is illustrated in Figure 7-1.

FIGURE 7-1: INTERRUPT CONTROLLER MODULE BLOCK DIAGRAM

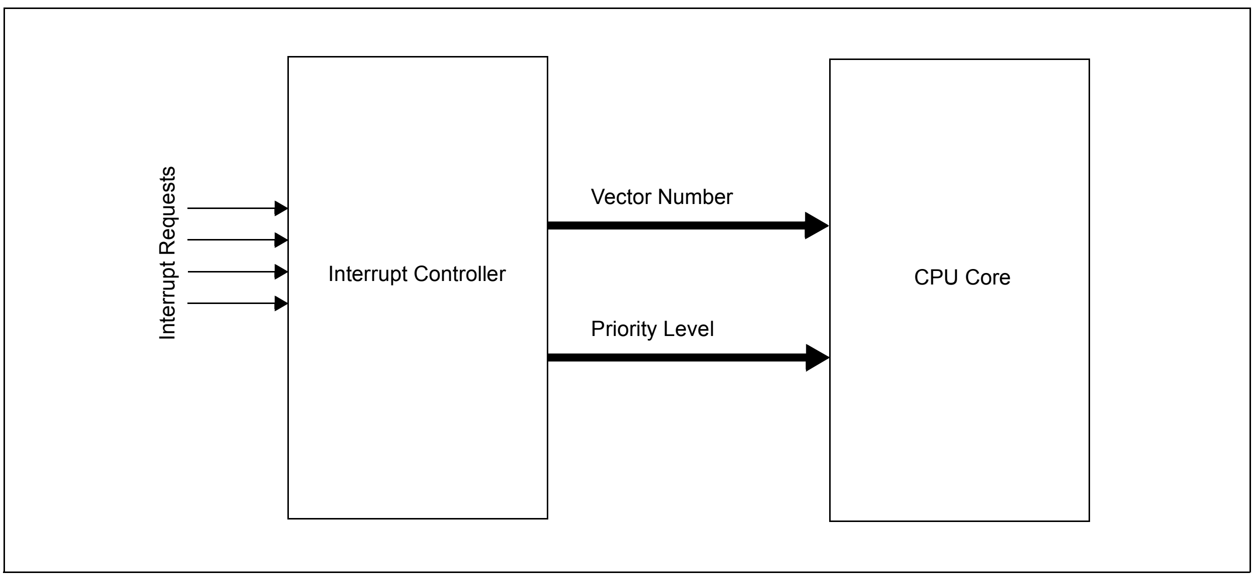
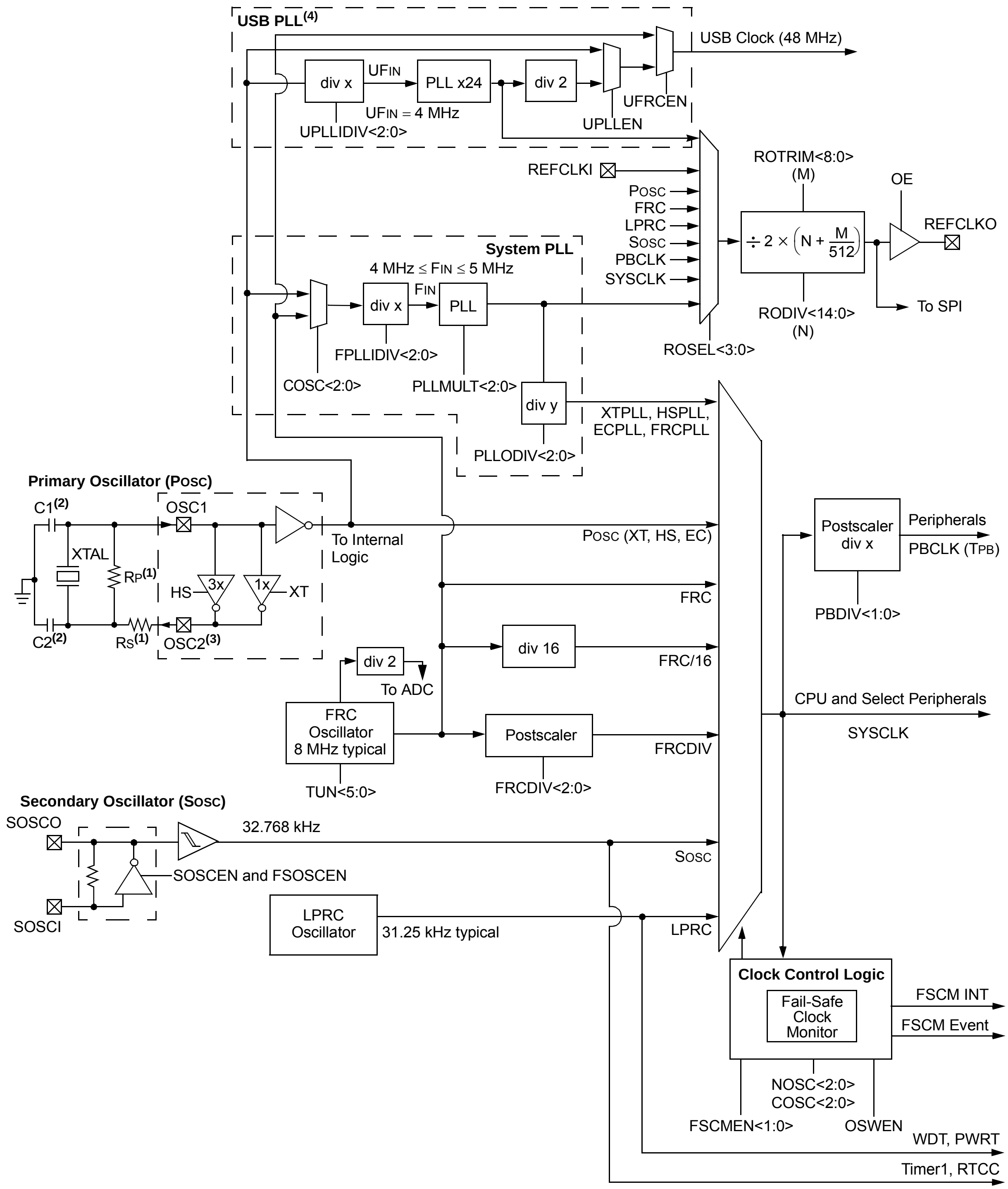


FIGURE 8-1: OSCILLATOR DIAGRAM



Notes:
1. A series resistor, RS, may be required for AT strip cut crystals or eliminate clipping. Alternately, to increase oscillator circuit gain, add a parallel resistor, RP, with a value of 1 MΩ.
2. Refer to **Section 6. "Oscillator Configuration"** (DS60001112) in the "*PIC32 Family Reference Manual*" for help in determining the best oscillator components.
3. The PBCLK out is only available on the OSC2 pin in certain clock modes.
4. The USB PLL is only available on PIC32MX2XX devices.

REGISTER 8-2: OSCTUN: FRC TUNING REGISTER

Bit Range	Bit 31/23/15/7	Bit 30/22/14/6	Bit 29/21/13/5	Bit 28/20/12/4	Bit 27/19/11/3	Bit 26/18/10/2	Bit 25/17/9/1	Bit 24/16/8/0
31:24	U-0	U-0	U-0	U-0	U-0	U-0	U-0	U-0
	—	—	—	—	—	—	—	—
23:16	U-0	R-0	U-0	U-0	U-0	U-0	U-0	U-0
	—	—	—	—	—	—	—	—
15:8	U-0	R-0	U-0	U-0	U-0	U-0	U-0	U-0
	—	—	—	—	—	—	—	—
7:0	U-0	U-0	R/W-0	R/W-0	R/W-0	R/W-0	R/W-0	R/W-0
	—	—	TUN<5:0>(1)					

Legend:			
R = Readable bit	W = Writable bit	U = Unimplemented bit, read as ‘0’	
-n = Value at POR	‘1’ = Bit is set	‘0’ = Bit is cleared	x = Bit is unknown

bit 31-6 **Unimplemented:** Read as ‘0’

bit 5-0 **TUN<5:0>:** FRC Oscillator Tuning bits(1)

100000 = Center frequency -12.5%
100001 =
•
•
•
111111 =
000000 = Center frequency. Oscillator runs at minimal frequency (8 MHz)
000001 =
•
•
•
011110 =
011111 = Center frequency +12.5%

Note 1: OSCTUN functionality has been provided to help customers compensate for temperature effects on the FRC frequency over a wide range of temperatures. The tuning step size is an approximation, and is neither characterized, nor tested.

Note: Writes to this register require an unlock sequence. Refer to **Section 6. “Oscillator”** (DS60001112) in the *“PIC32 Family Reference Manual”* for details.

REGISTER 9-4: DCRCCON: DMA CRC CONTROL REGISTER (CONTINUED)

bit 6 **CRCAPP:** CRC Append Mode bit(1)
1 = The DMA transfers data from the source into the CRC but NOT to the destination. When a block transfer completes the DMA writes the calculated CRC value to the location given by CHxDSA
0 = The DMA transfers data from the source through the CRC obeying WBO as it writes the data to the destination

bit 5 **CRCTYP:** CRC Type Selection bit
1 = The CRC module will calculate an IP header checksum
0 = The CRC module will calculate a LFSR CRC

bit 4-3 **Unimplemented:** Read as ‘0’

bit 2-0 **CRCCH<2:0>:** CRC Channel Select bits
111 = CRC is assigned to Channel 7
110 = CRC is assigned to Channel 6
101 = CRC is assigned to Channel 5
100 = CRC is assigned to Channel 4
011 = CRC is assigned to Channel 3
010 = CRC is assigned to Channel 2
001 = CRC is assigned to Channel 1
000 = CRC is assigned to Channel 0

Note 1: When WBO = 1, unaligned transfers are not supported and the CRCAPP bit cannot be set.

REGISTER 10-11: U1CON: USB CONTROL REGISTER

Bit Range	Bit 31/23/15/7	Bit 30/22/14/6	Bit 29/21/13/5	Bit 28/20/12/4	Bit 27/19/11/3	Bit 26/18/10/2	Bit 25/17/9/1	Bit 24/16/8/0
31:24	U-0	U-0	U-0	U-0	U-0	U-0	U-0	U-0
	—	—	—	—	—	—	—	—
23:16	U-0	U-0	U-0	U-0	U-0	U-0	U-0	U-0
	—	—	—	—	—	—	—	—
15:8	U-0	U-0	U-0	U-0	U-0	U-0	U-0	U-0
	—	—	—	—	—	—	—	—
7:0	R-x	R-x	R/W-0	R/W-0	R/W-0	R/W-0	R/W-0	R/W-0
	JSTATE	SE0	PKTDIS(4) TOKBUSY(1,5)	USBRST	HOSTEN(2)	RESUME(3)	PPBRST	USBEN(4) SOFEN(5)

Legend:			
R = Readable bit	W = Writable bit	U = Unimplemented bit, read as ‘0’	
-n = Value at POR	‘1’ = Bit is set	‘0’ = Bit is cleared	x = Bit is unknown

bit 31-8 **Unimplemented:** Read as ‘0’

bit 7 **JSTATE:** Live Differential Receiver JSTATE flag bit
1 = JSTATE was detected on the USB
0 = No JSTATE was detected

bit 6 **SE0:** Live Single-Ended Zero flag bit
1 = Single-Ended Zero was detected on the USB
0 = No Single-Ended Zero was detected

bit 5 **PKTDIS:** Packet Transfer Disable bit(4)
1 = Token and packet processing is disabled (set upon SETUP token received)
0 = Token and packet processing is enabled

TOKBUSY: Token Busy Indicator bit(1,5)
1 = Token is being executed by the USB module
0 = No token is being executed

bit 4 **USBRST:** Module Reset bit(5)
1 = USB reset generated
0 = USB reset terminated

bit 3 **HOSTEN:** Host Mode Enable bit(2)
1 = USB host capability is enabled
0 = USB host capability is disabled

bit 2 **RESUME:** RESUME Signaling Enable bit(3)
1 = RESUME signaling is activated
0 = RESUME signaling is disabled

Note 1: Software is required to check this bit before issuing another token command to the U1TOK register (see Register 10-15).
2: All host control logic is reset any time that the value of this bit is toggled.
3: Software must set RESUME for 10 ms if the part is a function, or for 25 ms if the part is a host, and then clear it to enable remote wake-up. In Host mode, the USB module will append a Low-Speed EOP to the RESUME signaling when this bit is cleared.
4: Device mode.
5: Host mode.

15.1 Input Capture Control Registers

TABLE 15-1: INPUT CAPTURE 1-INPUT CAPTURE 5 REGISTER MAP

Virtual Address (BF80_#)	Register Name	Bit Range	Bits																All Resets
			31/15	30/14	29/13	28/12	27/11	26/10	25/9	24/8	23/7	22/6	21/5	20/4	19/3	18/2	17/1	16/0	
2000	IC1CON(1)	31:16	—	—	—	—	—	—	—	—	—	—	—	—	—	—	—	—	0000
		15:0	ON	—	SIDL	—	—	—	FEDGE	C32	ICTMR	ICI<1:0>		ICOV	ICBNE	ICM<2:0>			0000
2010	IC1BUF	31:16	IC1BUF<31:0>																xxxx
		15:0																	xxxx
2200	IC2CON(1)	31:16	—	—	—	—	—	—	—	—	—	—	—	—	—	—	—	—	0000
		15:0	ON	—	SIDL	—	—	—	FEDGE	C32	ICTMR	ICI<1:0>		ICOV	ICBNE	ICM<2:0>			0000
2210	IC2BUF	31:16	IC2BUF<31:0>																xxxx
		15:0																	xxxx
2400	IC3CON(1)	31:16	—	—	—	—	—	—	—	—	—	—	—	—	—	—	—	—	0000
		15:0	ON	—	SIDL	—	—	—	FEDGE	C32	ICTMR	ICI<1:0>		ICOV	ICBNE	ICM<2:0>			0000
2410	IC3BUF	31:16	IC3BUF<31:0>																xxxx
		15:0																	xxxx
2600	IC4CON(1)	31:16	—	—	—	—	—	—	—	—	—	—	—	—	—	—	—	—	0000
		15:0	ON	—	SIDL	—	—	—	FEDGE	C32	ICTMR	ICI<1:0>		ICOV	ICBNE	ICM<2:0>			0000
2610	IC4BUF	31:16	IC4BUF<31:0>																xxxx
		15:0																	xxxx
2800	IC5CON(1)	31:16	—	—	—	—	—	—	—	—	—	—	—	—	—	—	—	—	0000
		15:0	ON	—	SIDL	—	—	—	FEDGE	C32	ICTMR	ICI<1:0>		ICOV	ICBNE	ICM<2:0>			0000
2810	IC5BUF	31:16	IC5BUF<31:0>																xxxx
		15:0																	xxxx

Legend: x = unknown value on Reset; — = unimplemented, read as '0'. Reset values are shown in hexadecimal.

Note 1: This register has corresponding CLR, SET and INV registers at its virtual address, plus an offset of 0x4, 0x8 and 0xC, respectively. See **Section 11.2 "CLR, SET and INV Registers"** for more information.

REGISTER 17-1: SPIxCON: SPI CONTROL REGISTER (CONTINUED)

bit 17 **SPIFE:** Frame Sync Pulse Edge Select bit (Framed SPI mode only)
1 = Frame synchronization pulse coincides with the first bit clock
0 = Frame synchronization pulse precedes the first bit clock

bit 16 **ENHBUF:** Enhanced Buffer Enable bit(2)
1 = Enhanced Buffer mode is enabled
0 = Enhanced Buffer mode is disabled

bit 15 **ON:** SPI Peripheral On bit(1)
1 = SPI Peripheral is enabled
0 = SPI Peripheral is disabled

bit 14 **Unimplemented:** Read as ‘0’

bit 13 **SIDL:** Stop in Idle Mode bit
1 = Discontinue module operation when the device enters Idle mode
0 = Continue module operation when the device enters Idle mode

bit 12 **DISSDO:** Disable SDOx pin bit
1 = SDOx pin is not used by the module. Pin is controlled by associated PORT register
0 = SDOx pin is controlled by the module

bit 11-10 **MODE<32,16>:** 32/16-Bit Communication Select bits

When AUDEN = 1:

MODE32	MODE16	Communication
1	1	24-bit Data, 32-bit FIFO, 32-bit Channel/64-bit Frame
1	0	32-bit Data, 32-bit FIFO, 32-bit Channel/64-bit Frame
0	1	16-bit Data, 16-bit FIFO, 32-bit Channel/64-bit Frame
0	0	16-bit Data, 16-bit FIFO, 16-bit Channel/32-bit Frame

When AUDEN = 0:

MODE32	MODE16	Communication
1	x	32-bit
0	1	16-bit
0	0	8-bit

bit 9 **SMP:** SPI Data Input Sample Phase bit
Master mode (MSTEN = 1):
1 = Input data sampled at end of data output time
0 = Input data sampled at middle of data output time
Slave mode (MSTEN = 0):
SMP value is ignored when SPI is used in Slave mode. The module always uses SMP = 0.

To write a '1' to this bit, the MSTEN value = 1 must first be written.

bit 8 **CKE:** SPI Clock Edge Select bit(3)
1 = Serial output data changes on transition from active clock state to Idle clock state (see the CKP bit)
0 = Serial output data changes on transition from Idle clock state to active clock state (see the CKP bit)

bit 7 **SSEN:** Slave Select Enable (Slave mode) bit
1 = $\overline{\text{SSx}}$ pin used for Slave mode
0 = $\overline{\text{SSx}}$ pin not used for Slave mode, pin controlled by port function.

bit 6 **CKP:** Clock Polarity Select bit(4)
1 = Idle state for clock is a high level; active state is a low level
0 = Idle state for clock is a low level; active state is a high level

Note 1: When using the 1:1 PBCLK divisor, the user’s software should not read or write the peripheral’s SFRs in the SYSCLK cycle immediately following the instruction that clears the module’s ON bit.

2: This bit can only be written when the ON bit = 0.

3: This bit is not used in the Framed SPI mode. The user should program this bit to ‘0’ for the Framed SPI mode (FRMEN = 1).

4: When AUDEN = 1, the SPI module functions as if the CKP bit is equal to ‘1’, regardless of the actual value of CKP.

REGISTER 22-1: AD1CON1: ADC CONTROL REGISTER 1 (CONTINUED)

bit 4 **CLRASAM:** Stop Conversion Sequence bit (when the first ADC interrupt is generated)
1 = Stop conversions when the first ADC interrupt is generated. Hardware clears the ASAM bit when the ADC interrupt is generated.
0 = Normal operation, buffer contents will be overwritten by the next conversion sequence

bit 3 **Unimplemented:** Read as '0'

bit 2 **ASAM:** ADC Sample Auto-Start bit
1 = Sampling begins immediately after last conversion completes; SAMP bit is automatically set.
0 = Sampling begins when SAMP bit is set

bit 1 **SAMP:** ADC Sample Enable bit(2)
1 = The ADC sample and hold amplifier is sampling
0 = The ADC sample/hold amplifier is holding
When ASAM = 0, writing '1' to this bit starts sampling.
When SSRC = 000, writing '0' to this bit will end sampling and start conversion.

bit 0 **DONE:** Analog-to-Digital Conversion Status bit(3)
1 = Analog-to-digital conversion is done
0 = Analog-to-digital conversion is not done or has not started
Clearing this bit will not affect any operation in progress.

Note 1: When using 1:1 PBCLK divisor, the user's software should not read/write the peripheral's SFRs in the SYSCLK cycle immediately following the instruction that clears the module's ON bit.

2: If ASAM = 0, software can write a '1' to start sampling. This bit is automatically set by hardware if ASAM = 1. If SSRC = 0, software can write a '0' to end sampling and start conversion. If SSRC $\neq$ '0', this bit is automatically cleared by hardware to end sampling and start conversion.

3: This bit is automatically set by hardware when analog-to-digital conversion is complete. Software can write a '0' to clear this bit (a write of '1' is not allowed). Clearing this bit does not affect any operation already in progress. This bit is automatically cleared by hardware at the start of a new conversion.

REGISTER 25-1: CTMUCON: CTMU CONTROL REGISTER

Bit Range	Bit 31/23/15/7	Bit 30/22/14/6	Bit 29/21/13/5	Bit 28/20/12/4	Bit 27/19/11/3	Bit 26/18/10/2	Bit 25/17/9/1	Bit 24/16/8/0
31:24	R/W-0	R/W-0	R/W-0	R/W-0	R/W-0	R/W-0	R/W-0	R/W-0
	EDG1MOD	EDG1POL	EDG1SEL<3:0>				EDG2STAT	EDG1STAT
23:16	R/W-0	R/W-0	R/W-0	R/W-0	R/W-0	R/W-0	U-0	U-0
	EDG2MOD	EDG2POL	EDG2SEL<3:0>				—	—
15:8	R/W-0	U-0	R/W-0	R/W-0	R/W-0	R/W-0	R/W-0	R/W-0
	ON	—	CTMUSIDL	TGEN(1)	EDGEN	EDGSEQEN	IDISSEN(2)	CTTRIG
7:0	R/W-0	R/W-0	R/W-0	R/W-0	R/W-0	R/W-0	R/W-0	R/W-0
	ITRIM<5:0>						IRNG<1:0>	

Legend:			
R = Readable bit	W = Writable bit	U = Unimplemented bit, read as ‘0’	
-n = Value at POR	‘1’ = Bit is set	‘0’ = Bit is cleared	x = Bit is unknown

bit 31 **EDG1MOD:** Edge1 Edge Sampling Select bit
1 = Input is edge-sensitive
0 = Input is level-sensitive

bit 30 **EDG1POL:** Edge 1 Polarity Select bit
1 = Edge1 programmed for a positive edge response
0 = Edge1 programmed for a negative edge response

bit 29-26 **EDG1SEL<3:0>:** Edge 1 Source Select bits
1111 = C3OUT pin is selected
1110 = C2OUT pin is selected
1101 = C1OUT pin is selected
1100 = IC3 Capture Event is selected
1011 = IC2 Capture Event is selected
1010 = IC1 Capture Event is selected
1001 = CTED8 pin is selected
1000 = CTED7 pin is selected
0111 = CTED6 pin is selected
0110 = CTED5 pin is selected
0101 = CTED4 pin is selected
0100 = CTED3 pin is selected
0011 = CTED1 pin is selected
0010 = CTED2 pin is selected
0001 = OC1 Compare Event is selected
0000 = Timer1 Event is selected

bit 25 **EDG2STAT:** Edge2 Status bit
Indicates the status of Edge2 and can be written to control edge source
1 = Edge2 has occurred
0 = Edge2 has not occurred

Note 1: When this bit is set for Pulse Delay Generation, the EDG2SEL<3:0> bits must be set to ‘1110’ to select C2OUT.

2: The ADC module Sample and Hold capacitor is not automatically discharged between sample/conversion cycles. Software using the ADC as part of a capacitive measurement, must discharge the ADC capacitor before conducting the measurement. The IDISSEN bit, when set to ‘1’, performs this function. The ADC module must be sampling while the IDISSEN bit is active to connect the discharge sink to the capacitor array.

3: Refer to the CTMU Current Source Specifications (Table 30-41) in **Section 30.0 “Electrical Characteristics”** for current values.

4: This bit setting is not available for the CTMU temperature diode.

NOTES:

27.3 On-Chip Voltage Regulator

All PIC32MX1XX/2XX 28/36/44-pin Family devices' core and digital logic are designed to operate at a nominal 1.8V. To simplify system designs, most devices in the PIC32MX1XX/2XX 28/36/44-pin Family family incorporate an on-chip regulator providing the required core logic voltage from VDD.

A low-ESR capacitor (such as tantalum) must be connected to the VCAP pin (see Figure 27-1). This helps to maintain the stability of the regulator. The recommended value for the filter capacitor is provided in **Section 30.1 "DC Characteristics"**.

Note:	It is important that the low-ESR capacitor is placed as close as possible to the VCAP pin.

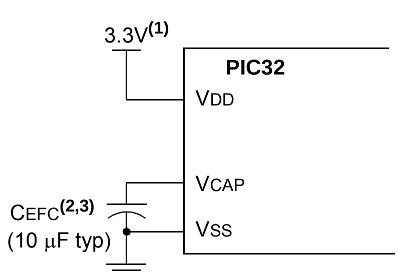
27.3.1 ON-CHIP REGULATOR AND POR

It takes a fixed delay for the on-chip regulator to generate an output. During this time, designated as TPU, code execution is disabled. TPU is applied every time the device resumes operation after any power-down, including Sleep mode.

27.3.2 ON-CHIP REGULATOR AND BOR

PIC32MX1XX/2XX 28/36/44-pin Family devices also have a simple brown-out capability. If the voltage supplied to the regulator is inadequate to maintain a regulated level, the regulator Reset circuitry will generate a Brown-out Reset. This event is captured by the BOR flag bit (RCON<1>). The brown-out voltage levels are specific in **Section 30.1 "DC Characteristics"**.

FIGURE 27-1: CONNECTIONS FOR THE ON-CHIP REGULATOR



Note 1: These are typical operating voltages. Refer to **Section 30.1 "DC Characteristics"** for the full operating ranges of VDD.
2: It is important that the low-ESR capacitor is placed as close as possible to the VCAP pin.
3: The typical voltage on the VCAP pin is 1.8V.

27.4 Programming and Diagnostics

PIC32MX1XX/2XX 28/36/44-pin Family devices provide a complete range of programming and diagnostic features that can increase the flexibility of any application using them. These features allow system designers to include:

- Simplified field programmability using two-wire In-Circuit Serial Programming™ (ICSP™) interfaces
- Debugging using ICSP
- Programming and debugging capabilities using the EJTAG extension of JTAG
- JTAG boundary scan testing for device and board diagnostics

PIC32 devices incorporate two programming and diagnostic modules, and a trace controller, that provide a range of functions to the application developer.

Figure 27-2 illustrates a block diagram of the programming, debugging, and trace ports.

FIGURE 27-2: BLOCK DIAGRAM OF PROGRAMMING, DEBUGGING AND TRACE PORTS

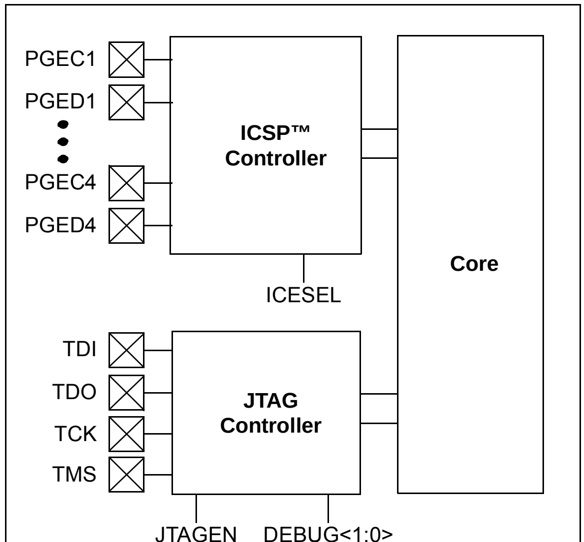


TABLE 30-7: DC CHARACTERISTICS: POWER-DOWN CURRENT (IPD)

DC CHARACTERISTICS			Standard Operating Conditions: 2.3V to 3.6V (unless otherwise stated) Operating temperature -40°C ≤ TA ≤ +85°C for Industrial -40°C ≤ TA ≤ +105°C for V-temp		
Param. No.	**Typical(2)**	**Max.**	**Units**	**Conditions**	
Power-Down Current (IPD) (Notes 1, 5)					
DC40k	44	70	µA	-40°C	Base Power-Down Current
DC40l	44	70	µA	+25°C	
DC40n	168	259	µA	+85°C	
DC40m	335	536	µA	+105ºC	
Module Differential Current					
DC41e	5	20	µA	3.6V	Watchdog Timer Current: ΔIWDT **(Note 3)**
DC42e	23	50	µA	3.6V	RTCC + Timer1 w/32 kHz Crystal: ΔIRTCC **(Note 3)**
DC43d	1000	1100	µA	3.6V	ADC: ΔIADC **(Notes 3,4)**

Note 1: The test conditions for IPD current measurements are as follows:
- Oscillator mode is EC (for 8 MHz and below) and EC+PLL (for above 8 MHz) with OSC1 driven by external square wave from rail-to-rail, (OSC1 input clock input over/undershoot < 100 mV required)
- OSC2/CLKO is configured as an I/O input pin
- USB PLL oscillator is disabled if the USB module is implemented, PBCLK divisor = 1:8
- CPU is in Sleep mode, and SRAM data memory Wait states = 1
- No peripheral modules are operating, (ON bit = 0), but the associated PMD bit is set
- WDT, Clock Switching, Fail-Safe Clock Monitor, and Secondary Oscillator are disabled
- All I/O pins are configured as inputs and pulled to VSS
- $\overline{\text{MCLR}}$ = VDD
- RTCC and JTAG are disabled

2: Data in the “Typical” column is at 3.3V, 25°C unless otherwise stated. Parameters are for design guidance only and are not tested.

3: The Δ current is the additional current consumed when the module is enabled. This current should be added to the base IPD current.

4: Test conditions for ADC module differential current are as follows: Internal ADC RC oscillator enabled.

5: IPD electrical characteristics for devices with 256 KB Flash are only provided as Preliminary information.

32.0 DC AND AC DEVICE CHARACTERISTICS GRAPHS

Note:	The graphs provided following this note are a statistical summary based on a limited number of samples and are provided for design guidance purposes only. The performance characteristics listed herein are not tested or guaranteed. In some graphs, the data presented may be outside the specified operating range (e.g., outside specified power supply range) and therefore, outside the warranted range.

FIGURE 32-1: I/O OUTPUT VOLTAGE HIGH (V_{OH})

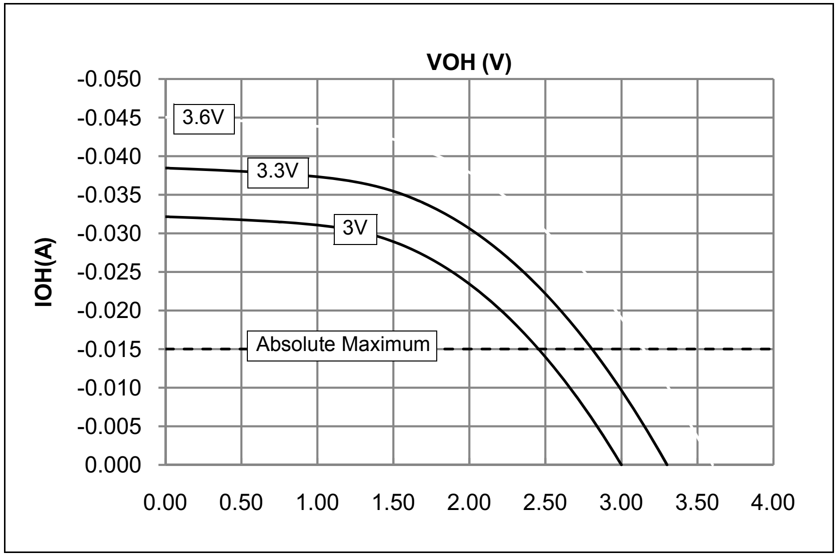


FIGURE 32-2: I/O OUTPUT VOLTAGE LOW (V_{OL})

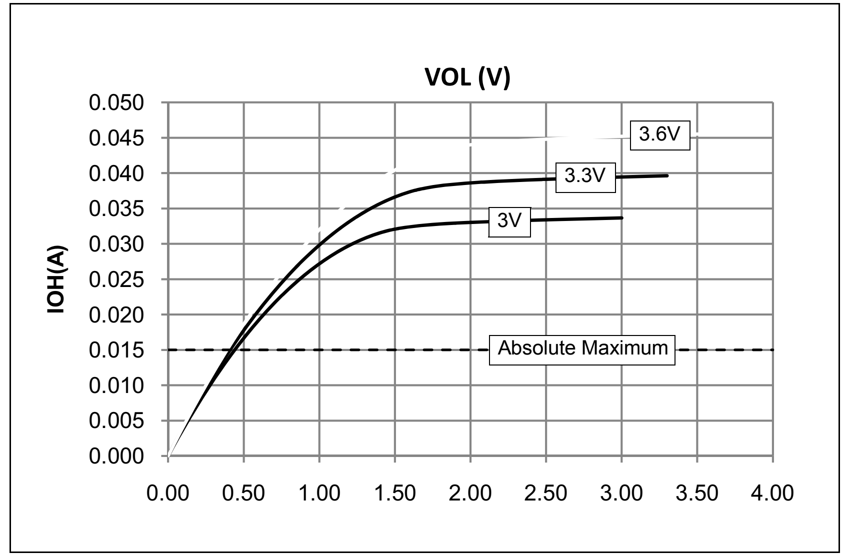


TABLE A-1: MAJOR SECTION UPDATES (CONTINUED)

Section	Update Description
4.0 “Memory Organization”	Added Memory Maps for the new devices (see Figure 4-3 and Figure 4-4). Removed the BMXCHEDMA bit from the Bus Matrix Register map (see Table 4-1). Added the REFOTRIM register, added the DIVSWEN bit to the REFOCON registers, added Note 4 to the ULOCK and SOSCEN bits and added the PBDIVRDY bit in the OSCCON register in the in the System Control Register map (see Table 4-16). Removed the ALTI2C1 and ALTI2C2 bits from the DEVCFG3 register and added Note 1 to the UPLLEN and UPLLIDIV<2:0> bits of the DEVCFG2 register in the Device Configuration Word Summary (see Table 4-17). Updated Note 1 in the Device and Revision ID Summary (see Table 4-18). Added Note 2 to the PORTA Register map (see Table 4-19). Added the ANSB6 and ANSB12 bits to the ANSELB register in the PORTB Register map (see Table 4-20). Added Notes 2 and 3 to the PORTC Register map (see Table 4-21). Updated all register names in the Peripheral Pin Select Register map (see Table 4-23). Added values in support of new devices (16 KB RAM and 32 KB RAM) in the Data RAM Size register (see Register 4-5). Added values in support of new devices (64 KB Flash and 128 KB Flash) in the Data RAM Size register (see Register 4-5).
8.0 “Oscillator Configuration”	Added Note 5 to the PIC32MX1XX/2XX Family Clock Diagram (see Figure 8-1). Added the PBDIVRDY bit and Note 2 to the Oscillator Control register (see Register 8-1). Added the DIVSWEN bit and Note 3 to the Reference Oscillator Control register (see Register 8-3). Added the REFOTRIM register (see Register 8-4).
21.0 “10-bit Analog-to-Digital Converter (ADC)”	Updated the ADC1 Module Block Diagram (see Figure 21-1). Updated the Notes in the ADC Input Select register (see Register 21-4).
24.0 “Charge Time Measurement Unit (CTMU)”	Updated the CTMU Block Diagram (see Figure 24-1). Added Note 3 to the CTMU Control register (see Register 24-1)
26.0 “Special Features”	Added Note 1 and the PGEC4/PGED4 pin pair to the ICESEL<1:0> bits in DEVCFG0: Device Configuration Word 0 (see Register 26-1). Removed the ALTI2C1 and ALTI2C2 bits from the Device Configuration Word 3 register (see Register 26-4). Removed 26.3.3 “Power-up Requirements”. Added Note 3 to the Connections for the On-Chip Regulator diagram (see Figure 26-2). Updated the Block Diagram of Programming, Debugging and Trace Ports diagram (see Figure 26-3).

TABLE A-1: MAJOR SECTION UPDATES (CONTINUED)

Section	Update Description
29.0 "Electrical Characteristics"	Updated the Absolute Maximum Ratings (removed Voltage on VCORE with respect to VSS). Added the SPDIP specification to the Thermal Packaging Characteristics (see Table 29-2). Updated the Typical values for parameters DC20-DC24 in the Operating Current (IDD) specification (see Table 29-5). Updated the Typical values for parameters DC30a-DC34a in the Idle Current (IIDLE) specification (see Table 29-6). Updated the Typical values for parameters DC40i and DC40n and removed parameter DC40m in the Power-down Current (IPD) specification (see Table 29-7). Removed parameter D320 (VCORE) from the Internal Voltage Regulator Specifications and updated the Comments (see Table 29-13). Updated the Minimum, Typical, and Maximum values for parameter F20b in the Internal FRC Accuracy specification (see Table 29-17). Removed parameter SY01 (TPWRT) and removed all Conditions from Resets Timing (see Table 29-20). Updated all parameters in the CTMU Specifications (see Table 29-39).
31.0 "Packaging Information"	Added the 28-lead SPDIP package diagram information (see **31.1 "Package Marking Information"** and **31.2 "Package Details"**).
"Product Identification System**"**	Added the SPDIP (SP) package definition.

Revision C (November 2011)

All major changes are referenced by their respective section in Table A-2.

TABLE A-2: MAJOR SECTION UPDATES

Section	Update Description
"32-bit Microcontrollers (up to 128 KB Flash and 32 KB SRAM) with Audio and Graphics Interfaces, USB, and Advanced Analog**"**	Revised the source/sink on I/O pins (see **"Input/Output"** on page 1). Added the SPDIP package to the PIC32MX220F032B device in the PIC32MX2XX USB Family Features (see Table 2).
4.0 "Memory Organization"	Removed ANSB6 from the ANSELB register and added the ODCB6, ODCB10, and ODCB11 bits in the PORTB Register Map (see Table 4-20).
29.0 "Electrical Characteristics"	Updated the minimum value for parameter OS50 in the PLL Clock Timing Specifications (see Table 29-16).

Revision J (April 2016)

This revision includes the following major changes as described in Table A-8, as well as minor updates to text and formatting, which were incorporated throughout the document.

TABLE A-8: MAJOR SECTION UPDATES

Section	Update Description
"32-bit Microcontrollers (up to 256 KB Flash and 64 KB SRAM) with Audio and Graphics Interfaces, USB, and Advanced Analog"	The PIC32MX270FDB device and Note 4 were added to **TABLE 2: "PIC32MX2XX 28/36/44-pin USB Family Features"**.
2.0 "Guidelines for Getting Started with 32-bit MCUs"	**EXAMPLE 2-1: "Crystal Load Capacitor Calculation"** was updated.
30.0 "Electrical Characteristics"	Parameter DO50a (C_{SOSC}) was removed from the Capacitive Loading Requirements on Output Pins AC Characteristics (see Table 30-16).
"Product Identification System"	The device mapping was updated to include type B for Software Targeting.

NOTES: